

SC77108BQ Single Channel 8-mΩ Smart High Side Driver with Advanced Protections and Diagnostics

1 Descriptions

The SC77108BQ is a fully-protected single channel smart high side driver qualified in automotive grade. Full diagnostics and high accuracy current sense enable intelligent control of the load even in harsh conditions. It integrates an 8mΩ MOSFET in a compact package size with advanced protections of overload protection, dynamic thermal swing shutdown, absolute thermal shutdown. It features auto-restart mode in fault events. A multiplexed pin delivers proportional current sense, or fault indications in both active mode and standby mode.

2 Features

- Qualified for Automotive Applications.
- AEC-Q100 Qualified with the Following Results:
 - Device Temperature Grade 1: -40°C to 125°C Ambient Operating Temperature Range
 - Device HBM ESD Classification Level H3A
 - Device CDM ESD Classification Level C4B
- Single Channel 8mΩ Smart High-Side Switch with Full Diagnostics:
 - 14-pins, Auto-restart Mode, Channel Fault Diagnosis, Proportional Load Current Sense Output.
- Operating Junction Temperature: -40 to 150°C
- Wide Operating Voltage from 4 to 28V with Load Dump Withstand Voltage up to 40V.
- Ultra Low Standby Current < 500 nA
- Input Control, 3.3 V and 5 V Logic Compatible
- High Accuracy Current Sense:
 - ±4.5% @ 6A
 - ±5% @ 1A
 - ±13% @ 0.1A
 - ±20% @ 0.05A
 - ±50% @ 0.02A
- Electrical Transient Disturbance Immunity Certification of ISO7637-2 and ISO16750-2

- Advanced Protections:
 - Short to GND and Overload Protection by internal Overcurrent Shutdown
 - Dynamic Thermal Swing Shutdown and Absolute Thermal Shutdown with Auto-restart Mode
 - Inductive Load Negative Voltage Clamp with Optimized Slew Rate
 - Loss of GND and Loss of Battery Protection
 - Under Voltage Lockout (UVLO) Protection
- Diagnostics:
 - Overload and Short to Ground Detection in Active Mode
 - Open Load and Short to Battery Detection in Standby Mode

3 Applications

- High Side Power Driver for Sub-module
- Power Switch for Automotive Lamp
- High Side Relays and Solenoids
- General Resistive, Inductive and Capacitive Loads

4 Device Information

ORDER NUMBER	DESCRIPTION	PACKAGE	BODY SIZE
SC77108BQSHER	<ul style="list-style-type: none"> Auto-restart Mode Channel Fault Diagnosis Output Proportional Load Current Sense Output 	eSSOP-14	5.2mm x 3.9 mm x 1.4mm

5 Revision History

Note: Page numbers for previous revisions may differ from page numbers in the current version.

Revision	Date	Page(s) changed	Changes Description
1.0	2024.12.19		Initial released
1.0.1	2025.6.4	5~7	8.5 Electrical Characteristics <ul style="list-style-type: none"> (1) Add superscripts “ (1) ” to some parameters, including “I_{LIML}”, “$I_{OUT,REV}$”, “$I_{OUT,INV}$”, “T_{SD}”, “T_R”, “T_{SW}”, “T_{HYS}”, “I_{SENSE_SAT}”. (2) Delete footnotes: <ul style="list-style-type: none"> 1. “The current includes... “ 2. “The accuracy of external... “ 3. “The external current limit ...” (3) Add new footnotes: “Parameter guaranteed by design ...” (4) “Turn-off Delay Time” Updated (Min./Typ.:30us/60us → Min./Typ.:20us/50us) (5) “Pulse Skew $t_{Pd_rise-t_{Pd,fall}}$” Updated (Min.: -50us → Min.: -65us)
1.0.2	2025.9.4	5~10	8.5 Electrical Characteristics <ul style="list-style-type: none"> (1) “Drain to source internal clamp voltage@-40℃” Updated (Min.:38V → Min.:36V) (2) “Drain to source internal clamp voltage@25~150℃” Updated (Min./Typ./Max.:42V/48V/52V → Min./Typ./Max.: 38V/43V/48V) (3) “Turn-off Delay Time” Updated (Min.:20us → Min.:25us) MECHANICAL DATA Updated <ul style="list-style-type: none"> (1) E2($2.29 \pm 0.30\text{mm}$ → $2.29 \pm 0.10\text{mm}$) (2) D1($3.30 \pm 0.30\text{mm}$ → $3.30 \pm 0.10\text{mm}$)
1.0.3	2026.03	2~22	Update the parameters name, function description in the datasheet

6 Typical Application Circuit

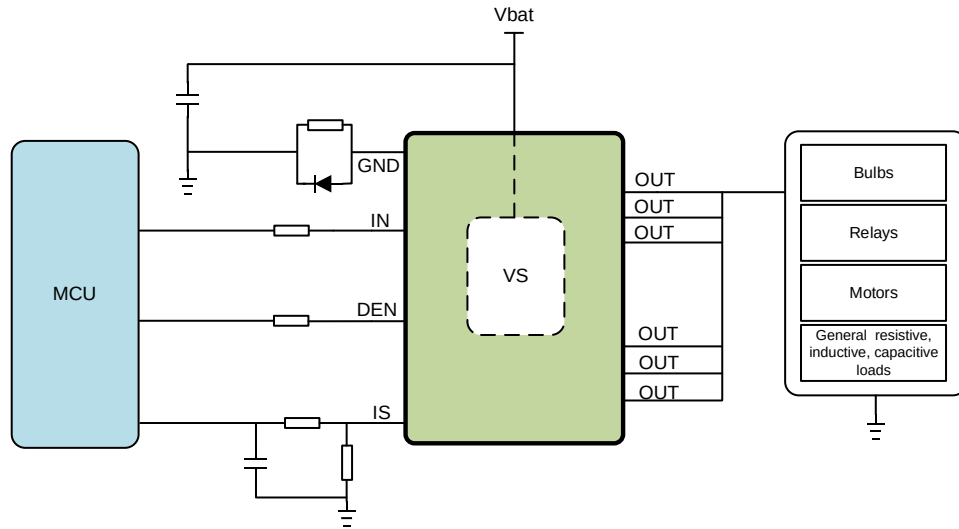
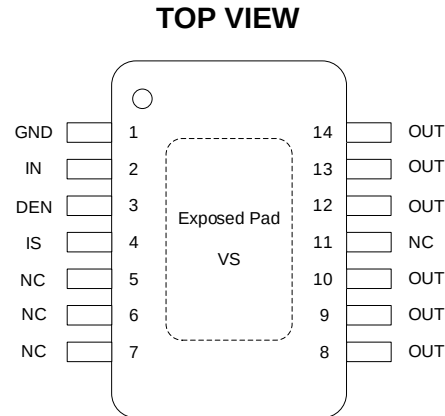


Figure 6-1. Typical Application Circuit

7 Terminal Configuration and Functions



NUMBER	TERMINAL NAME	I/O	DESCRIPTION
1	GND	-	Ground connection.
2	IN	I	Input pin. Active high to turn on Channel. If not used: connect to GND pin or to module ground with resistor $R_{IN} = 4.7\text{ k}\Omega$.
3	DEN	I	Diagnosis enable pin. Active high. If not used: connect to GND pin or to module ground with resistor $R_{DEN} = 4.7\text{ k}\Omega$.
4	IS	O	Multiplexed sense output. It delivers proportional current sense signals. Besides, fault indications are reported in Active Mode and Standby Mode. If not used: left open.
5	NC	-	Not connected.
6	NC	-	Not connected.
7	NC	-	Not connected.

8	OUT	O	Output of Channel.
9	OUT	O	Output of Channel.
10	OUT	O	Output of Channel.
11	NC	-	Not connected.
12	OUT	O	Output of Channel.
13	OUT	O	Output of Channel.
14	OUT	O	Output of Channel.
Exposed Pad	VS	I	Power supply connection.

8 Specifications

8.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted) ⁽¹⁾

PARAMETER	DEFINITION	MIN	MAX	UNIT
Voltage Range at Terminals ⁽²⁾	Supply Voltage ⁽³⁾	-0.3	40	V
	Reverse Polarity Voltage with External Blocking Diode ⁽⁴⁾	-18		V
	Supply Voltage for Short Circuit Protection		18	V
	Voltage on IN, DEN Pins	-0.3	7	V
	Voltage on IS Pin	-2.7	7	V
Current Range at Terminals ⁽²⁾	DC Current on OUT Pin ⁽⁵⁾		Internally limited	A
	Current on GND Pin	-50 -250 ⁽⁵⁾	50	mA
	Current on IN, DEN Pins	-20	20	mA
	Current on IS Pin	-25	30	mA
f _{IN,MAX}	PWM Frequency on IN Pin		2	kHz
E _{AS}	Inductive Load Switch-off Energy Dissipation, Single Pulse ⁽⁶⁾		45	mJ
T _A	Operating Ambient Temperature Range	-40	125	°C
T _J	Operating Junction Temperature Range	-40	150	°C
T _{STG}	Storage Temperature Range	-65	150	°C

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values are with respect to network ground terminal.
- (3) Supply voltage to withstand load dump test for 400ms, according to ISO 16750-2:2010 load dump Test B.
- (4) Reverse polarity condition: t < 60 s, reverse current < I_{L,REV}, GND pin 4.7-kΩ resistor in parallel with diode.
- (5) For limited time range: t < 120s
- (6) Test condition: VS = 28 V, IL = 2*I_{L,NOM}, T_J = 150°C. FR4 2s2p board, 2 × 70 μm Cu, 2 × 35 μm Cu. 600 mm² thermal pad copper area.

8.2 Handling Ratings

PARAMETER	DEFINITION		MIN	MAX	UNIT
ESD ⁽¹⁾	Human Body Model (HBM) ESD Stress Voltage ⁽²⁾	All Pins	-4	4	kV
	Charged Device Model (CDM) ESD Stress Voltage ⁽³⁾	All Pins	-750	750	V

- (1) Electrostatic discharge (ESD) to measure device sensitivity and immunity to damage caused by assembly line electrostatic discharges into the device.
- (2) Level listed above is the passing level per AEC-Q100-002. The human-body model is a 100-pF capacitor discharged through a 1.5-kΩ resistor into each terminal.
- (3) Level listed above is the passing level per AEC-Q100-011.

8.3 Recommended Operating Conditions

PARAMETER	DEFINITION	MIN	TYP	MAX	UNIT
V _S	Voltage on VS pin	5		28	V
V _{IH}	Input Logic High on IN, DEN Pins	2		5.5	V
V _{IL}	Input Logic Low on IN, DEN Pins	0		0.8	V
I _{L,NOM}	Nominal DC load current		10		A
T _A	Operating ambient temperature	-40		125	°C
T _J	Operating junction temperature	-40		150	°C

8.4 Thermal Information

THERMAL RESISTANCE ⁽¹⁾		eSSOP-14	UNIT
R _{ΘJA}	Junction to ambient thermal resistance ⁽²⁾	33.3	°C/W
R _{ΘJC(top)}	Junction to case(top) thermal resistance	24.3	°C/W
R _{ΘJC(bottom)}	Junction to case(bottom) thermal resistance	1.5	°C/W
R _{ΘJB}	Junction-to-board thermal resistance	9.4	°C/W
ψ _{JT}	Junction-to-top characterization parameter	3.2	°C/W
ψ _{JB}	Junction-to-board characterization parameter	9.3	°C/W

- (1) Measured on JESD51-7, 4-layer PCB.
- (2) The thermal data is based on JEDEC standard high-K profile – JESD 51-7. The copper pad is soldered to the thermal land pattern. Also, correct attachment procedure must be incorporated.

8.5 Electrical Characteristics

-40°C < T_J < 150°C and 5V < V_S < 28V unless otherwise noted.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
POWER SUPPLY VOLTAGE						
V _{S,NOM}	Normal Operating Voltage		5	13.5	28	V
V _{S,EXT}	Extended Operating Voltage	R _{on} and switching characteristics may vary compared to those in V _{S,NOM} , but protection functions are still operative.	4		5	V
V _{S,UVR}	Undervoltage Restart	V _S Rising threshold to exit undervoltage, V _{IN} = 5V	3.5	3.7	4	V
V _{S,UVF}	Undervoltage Shutdown	V _S Falling threshold to enter undervoltage, V _{IN} = 5V	3	3.2	3.5	V
V _{S,UVhys}	Undervoltage Shutdown Hysteresis	V _{S,UVR} - V _{S,UVF}		0.5		V
V _{S,JS} ⁽¹⁾	Power Supply Voltage Threshold for Overload Threshold Reduction in Case of Short Circuit		16.5	18	19.5	V
t _{D,SLEEP}	Blanking time into Sleep Mode	V _S = 13.5 V, V _{OUT} = 0 V, V _{IN} = 0 V, V _{DEN} = 5 V to 0 V		12		ms
OPERATING CURRENT						
I _{S,SLEEP}	Supply Current in Sleep Mode	V _S = 13.5V, V _{OUT} = 0V, V _{IN} = 0V, V _{DEN} = 0V, T _J = 25°C			0.5	μA
		V _S = 13.5V, V _{OUT} = 0V, V _{IN} = 0V, V _{DEN} = 0V, T _J = 125°C			3	μA
I _{GND,STBY}	Supply Current in Standby Mode	V _S = 13.5V, V _{OUT} = 0V, V _{IN} = 0V, V _{DEN} = 5V		1.8	3	mA
I _{S,ON}	Supply Current for No Load, No Diagnosis	V _S = 13.5V, I _L = 0A, V _{IN} = 5V, V _{DEN} = 0V		1.8	3	mA
I _{GND,ON}	Operating Current in Active Mode	V _S = 13.5V, I _L = 5 A, V _{IN} = 5 V, V _{DEN} = 5 V			3	mA
I _{L,OFF}	Output Leakage Current in Sleep Mode	V _S = 13.5V, V _{OUT} = 0V, V _{IN} = 0V, V _{DEN} = 0V, T _J = 25°C		0.01	0.5	μA
		V _S = 13.5V, V _{OUT} = 0V, V _{IN} = 0V, V _{DEN} = 0V, T _J = 125°C			3	μA
POWER STAGE						
R _{ON}	ON-state Resistance	V _S =13.5V, I _L = 5A, T _J = 25°C		8		mΩ
		V _S =13.5V, I _L = 5A, T _J = 150°C			17	mΩ
I _{LOVL}	Overload Detection Current	V _S = 13.5V	45	70	95	A
I _{LOVL,JS} ⁽¹⁾	Overload Detection Current Jump Start Condition	V _S > V _{S,JS}		23		A

I _{LOVL,TC} ⁽¹⁾	Current Limit during Thermal Cycling	V _S = 13 V; T _R < T _J < T _{SD}	23			A
V _{DS,CLP}	Drain to Source Clamp Voltage	I _L = 2A, T _J = -40°C	36			V
		I _L = 2A, T _J = 25°C ~150°C	38	43	48	V
OUTPUT DIODE CHARACTERISTICS						
V _{OUT,F}	Drain Source Diode Voltage	V _{IN} =0, I _L = -5A	0.7			V
I _{L,REV} ⁽¹⁾	Continuous Reverse Current when Reverse Polarity	t < 60s, V _S = 13.5V, GND pin 4.7kΩ resistor in parallel with diode. T _J = 25°C	5			A
I _{L,INV} ⁽¹⁾	Continuous Inverse Current When V _{OUT} > V _S + V _{OUT,F}	t < 120 s, V _S = 13.5 V, T _J = 25°C	5			A
LOGIC INPUT (IN, DEN)						
V _{IH}	Input Logic High		2			V
V _{IL}	Input Logic Low		0.8			V
V _{I,HYS}	Input Logic Hysteresis		150			mV
I _{IH}	High Level Pull-down Current	V _{IN} =2V	10			μA
I _{IL}	Low Level Pull-down Current	V _{IN} =0.8V	1	10		μA
DIAGNOSTICS AND PROTECTION						
I _{LOSS,GND}	Output Leakage Current when Loss of Ground	V _S = 13.5 V, V _{IN} = V _{DEN} = 3.3 V	100			μA
V _{OL,OFF}	Open Load Detection Threshold in Standby Mode (V _{OUT} -GND)	V _{IN} = 0 V, V _{DEN} = 5 V	2	3	4	V
I _{OL,OFF}	Standby Mode Output Sink Current with Open Load	V _S = 13.5 V, V _{OUT} = 4V, V _{IN} = 0 V, V _{DEN} = 5 V	-40			μA
t _{D,OL,IN}	Standby Mode Diagnostic Delay Time from Falling Edge of Input	V _S = 13.5 V, V _{OUT} = 13.5 V, V _{IN} = 5V to 0V, V _{DEN} = 5V	260	500	700	μs
t _{D,OL,VO}	Standby Mode Diagnostic Delay Time from Rising Edge of V _{OUT}	V _S = 13.5 V, V _{OUT} =0 to 4V, V _{IN} = 0 V, V _{DEN} = 5 V	150		220	μs
t _{D,OL,DEN}	Standby Mode Diagnostic Delay Time from Rising Edge of DEN	V _S = 13.5 V, V _{OUT} = V _S , V _{IN} = 0 V, V _{DEN} = 0 to 5 V	150		220	μs
T _{SD} ⁽¹⁾	Thermal Shutdown Temperature		170			°C
T _R ⁽¹⁾	Thermal Shutdown Reset Temperature		140			°C
T _{SW} ⁽¹⁾	Thermal Swing Shutdown Threshold		45			°C
T _{HYS} ⁽¹⁾	Hysteresis for Resetting the Thermal Shutdown and Swing		20			°C
Multiple SENSE Functions						
K _{IS}	Ratio of Current Sense		6000			

dK_{IS}/K_{IS}	Accuracy of Current Sense ($I_{IS} \times K_{IS} - I_L$) / $I_L \times 100$	$I_L = 0.02A$	-50	50	%
		$I_L = 0.05A$	-20	20	
		$I_L = 0.1A$	-13	13	
		$I_L = 1A$	-5	5	
		$I_L = 6A$	-4.5	4.5	
$V_{IS,SAT}$	IS Saturation Voltage	$V_S = 7V$ to $18V$; $R_{IS} = 1.2k\Omega$; $V_{IN} = 5V$, $V_{DEN} = 5V$	4.8		V
$V_{IS,H}$	Fault High Voltage of IS	$V_S \geq 7V$	5	5.5 6	V
		$5V \leq V_S < 7V$	4.3	6	V
$I_{IS,SAT}^{(1)}$	IS Saturation Current	$V_S = 7V$ to $18V$; $R_{IS} = 1.2k\Omega$; $V_{IN} = 5V$, $V_{DEN} = 5V$	4		mA
$I_{IS,FAULT}$	Fault Current of IS	$V_S = 7V$ to $18V$; $R_{IS} = 1.2k\Omega$; $V_{IN} = 5V$, $V_{DEN} = 5V$	10		mA
$I_{IS,OLOFF}$	Sense Open Load in Standby Mode	$V_S = 7V$ to $18V$; $R_{IS} = 1.2k\Omega$; $V_{IN} = 0V$, $V_{DEN} = 5V$	10		mA
$I_{IS,LEAK1}$	Leakage Current of IS in Diagnostic Disable State	$V_{IN} = 5V$, $V_{DEN} = 0V$, $V_{IS} = 0V$, $I_L = 5A$		0.5	μA
$I_{IS,LEAK2}$	Leakage Current of IS in Diagnostic Enable State	$V_{IN} = 5V$, $V_{DEN} = 5V$, $V_{IS} = 0V$, $I_L = 0A$, $T_J = 125^\circ C$		2	μA
$t_{IS,ON1}$	Current IS Settling Time from DEN Rising Edge	$I_L \geq 1A$, $R_{IS} = 1.2k\Omega$, $V_{IN} = 5V$, $V_{DEN} = 0$ to $5V$, V_{IS} to 90% of sense value		30	μs
$t_{IS,OFF1}$	Current IS Settling Time from DEN Falling Edge	$I_L \geq 1A$, $R_{IS} = 1.2k\Omega$, $V_{IN} = 5V$, $V_{DEN} = 5$ to $0V$, V_{IS} to 10% of sense value		20	μs
$t_{IS,FAULT,D}$	Sense Delay Time at Channel Switch ON after Last Fault Condition			350	μs
$t_{IS,ON2}$	Current Sense Settling Time from IN Rising Edge	$I_L \geq 1A$, $R_{IS} = 1.2k\Omega$, $V_{IN} = 0$ to $5V$, $V_{DEN} = 5V$, V_{IS} to 90% of sense value		150	μs
$t_{IS,OFF2}$	Current Sense Settling Time from IN Falling Edge	$I_L \geq 1A$, $R_{IS} = 1.2k\Omega$, $V_{IN} = 5$ to $0V$, $V_{DEN} = 5V$, V_{IS} to 10% of sense value		10	μs
Switching Characteristics					
$t_{D,ON}$	Turn-on Delay Time	V_{IN} rising edge to $V_{OUT} = 20\% \times V_S$, $V_S = 13.5V$, $R_L = 2.6\Omega$, $T_J = 25^\circ C$	30	55 100	μs
$t_{D,OFF}$	Turn-off Delay Time	V_{IN} falling edge to $V_{OUT} = 80\% \times V_S$, $V_S = 13.5V$, $R_L = 2.6\Omega$, $T_J = 25^\circ C$	25	50 120	μs
dV/dt_{ON}	Turn-on Slew Rate	$V_{OUT} = 20\%$ to 80% , $V_S = 13.5V$, $R_L = 2.6\Omega$, $T_J = 25^\circ C$	0.3	0.45 0.6	V/ μs

dV/dt_{OFF}	Turn-off Slew Rate	$V_{OUT}=80\%$ to 20% , $V_S=13.5\text{ V}$, $R_L=2.6\Omega$, $T_J=25^\circ\text{C}$	0.3	0.5	0.75	V/ μs
t_{skew}	Pulse Skew $t_{D,ON} - t_{D,OFF}$	$V_S=13.5\text{ V}$, $R_L=2.6\Omega$, $T_J=25^\circ\text{C}$	-65		65	μs

(1) Parameter guaranteed by design and characterization; not subject to production test.

8.6 Typical Characteristics

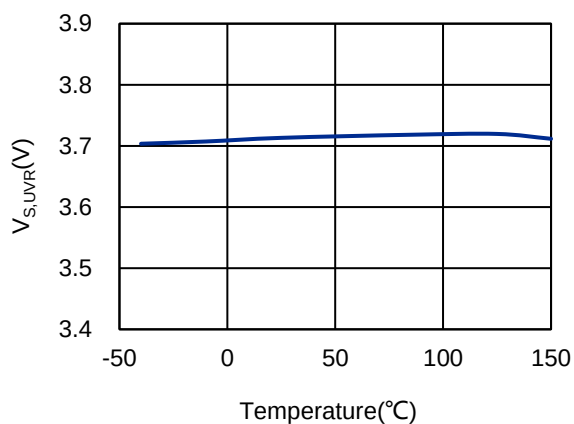


Figure 8-1. $V_{S,UVR}$ vs T_A

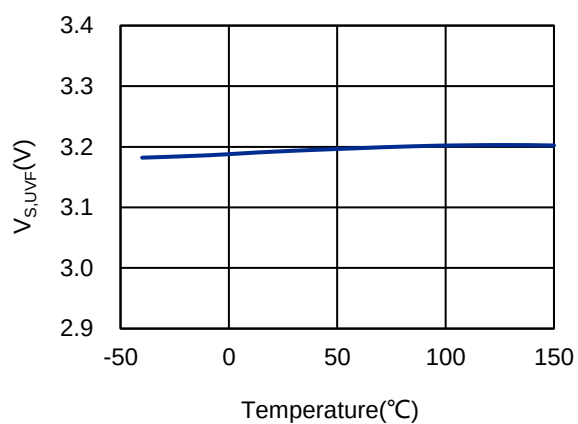


Figure 8-2. $V_{S,UVF}$ vs T_A

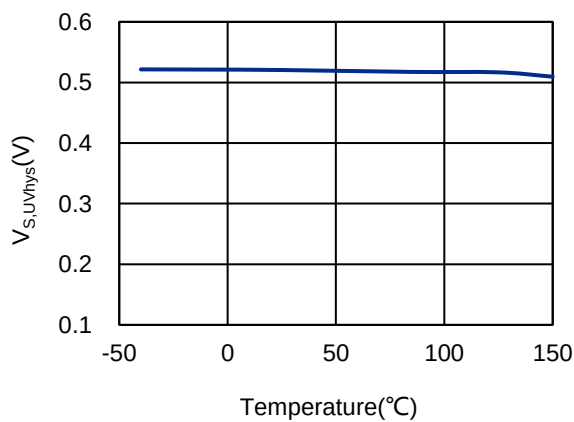


Figure 8-3. $V_{S,UVhys}$ vs T_A

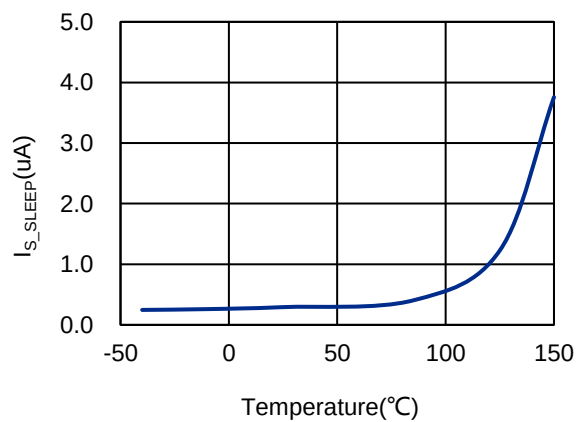


Figure 8-4. $I_{S,SLEEP}$ vs T_A

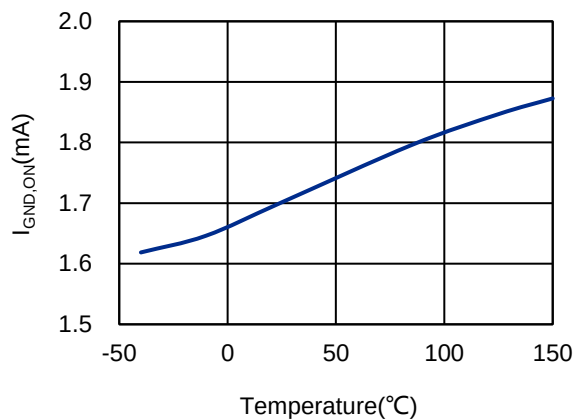


Figure 8-5. $I_{GND,ON}$ vs T_A

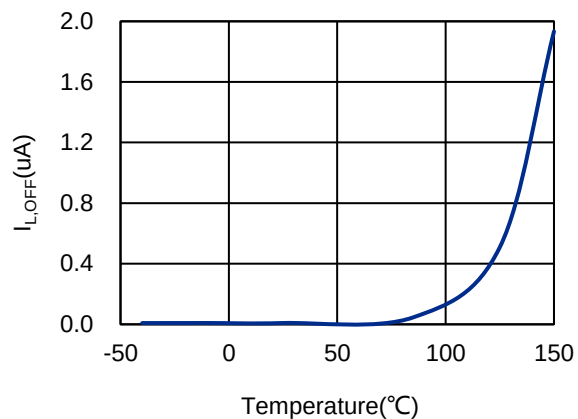


Figure 8-6. $I_{L,OFF}$ vs T_A

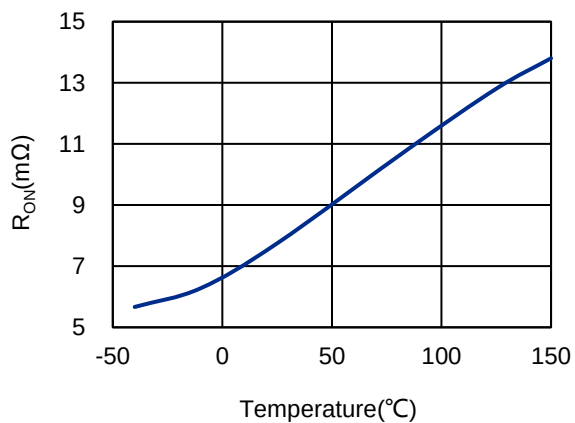


Figure 8-7. R_{ON} vs T_A

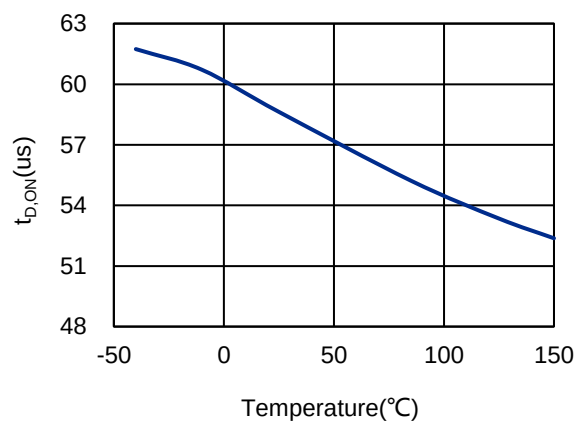


Figure 8-8. $t_{D,ON}$ vs T_A

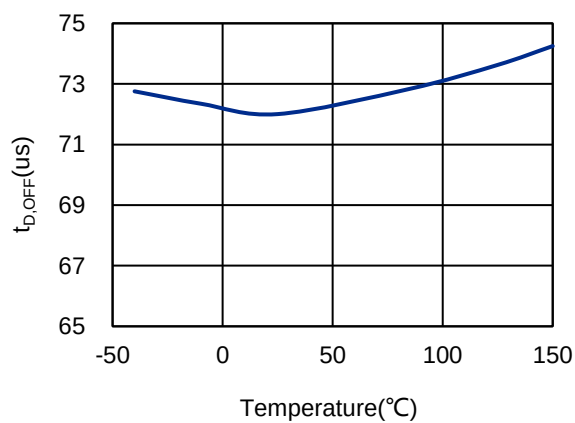


Figure 8-9. $t_{D,OFF}$ vs T_A

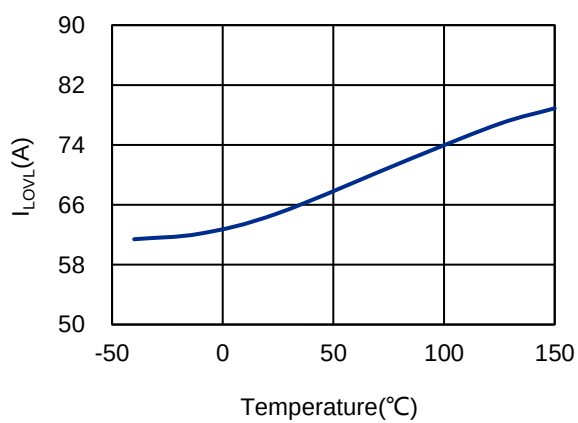


Figure 8-10. I_{LOVL} vs T_A

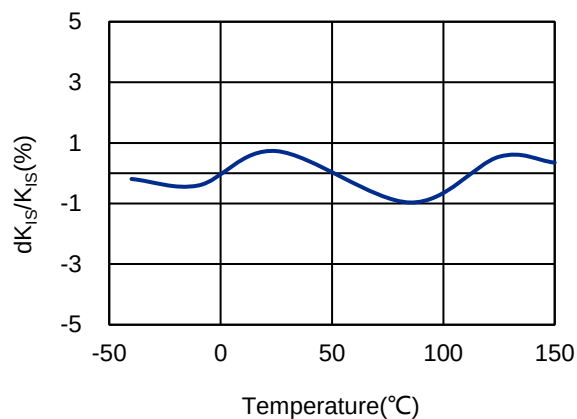


Figure 8-11. dK_{IS} / K_{IS} vs T_A ($I_L = 0.1A$)

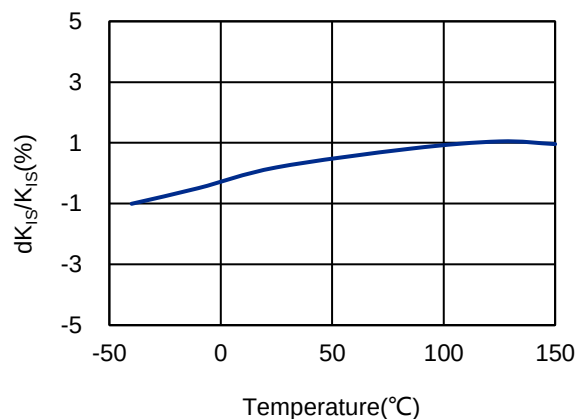


Figure 8-12. dK_{IS} / K_{IS} vs T_A ($I_L = 6A$)

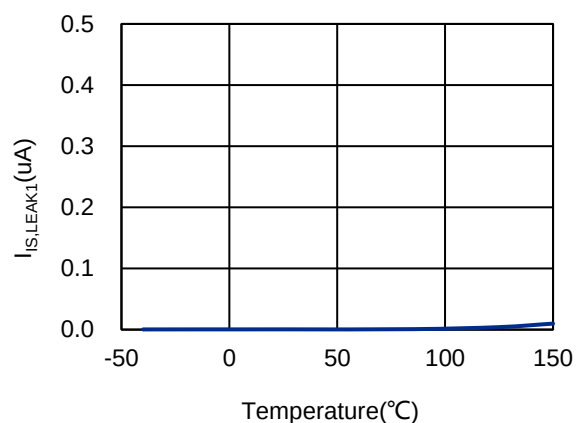


Figure 8-13. $I_{IS,LEAK1}$ vs T_A

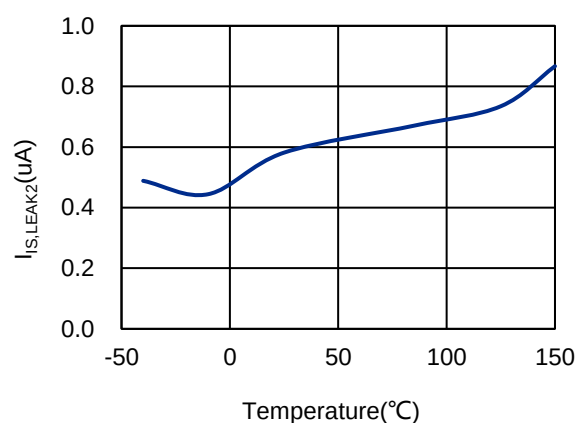


Figure 8-14. $I_{IS,LEAK2}$ vs T_A

9 Functional Block Diagram

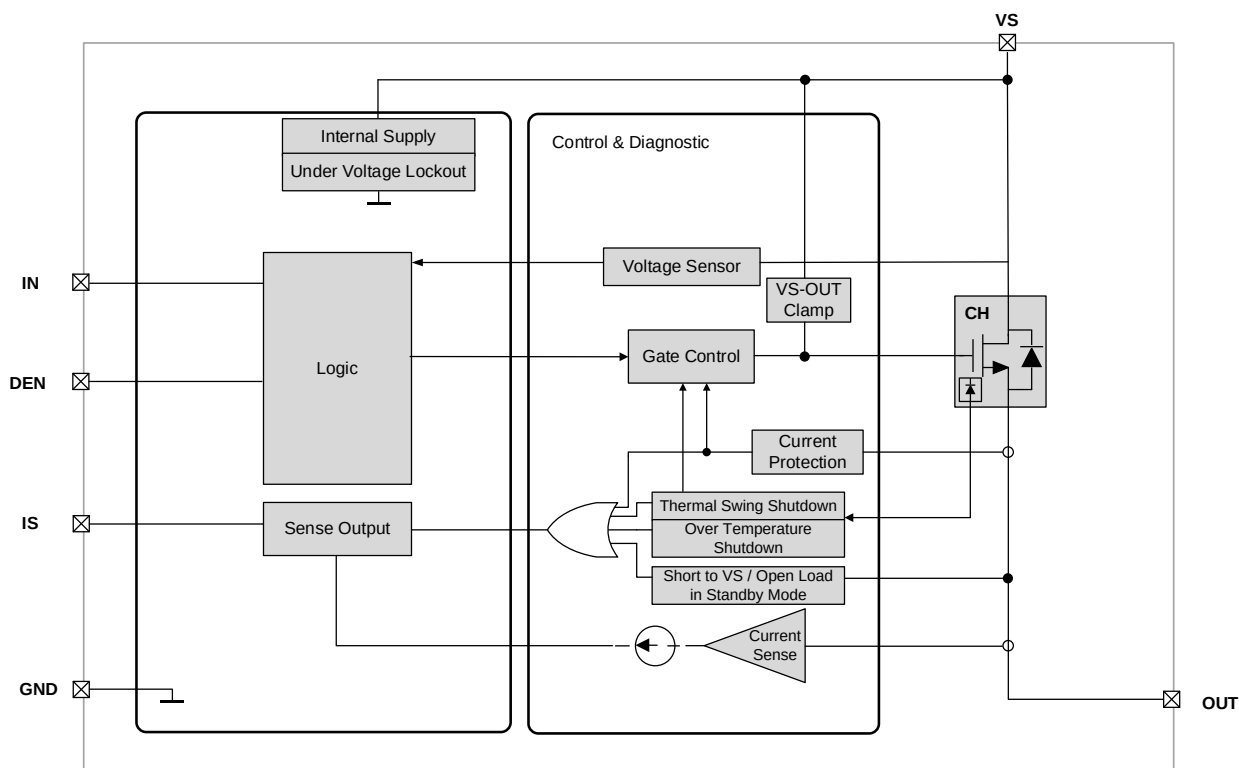


Figure 9-1. Functional Block Diagram

10 Feature Description

10.1 Operating States Diagram

The device has three operating states called 'Sleep Mode', 'Standby Mode' and 'Active Mode', which are decided by the logic level of IN pin and DEN pin, the operating mode diagram is shown as below.

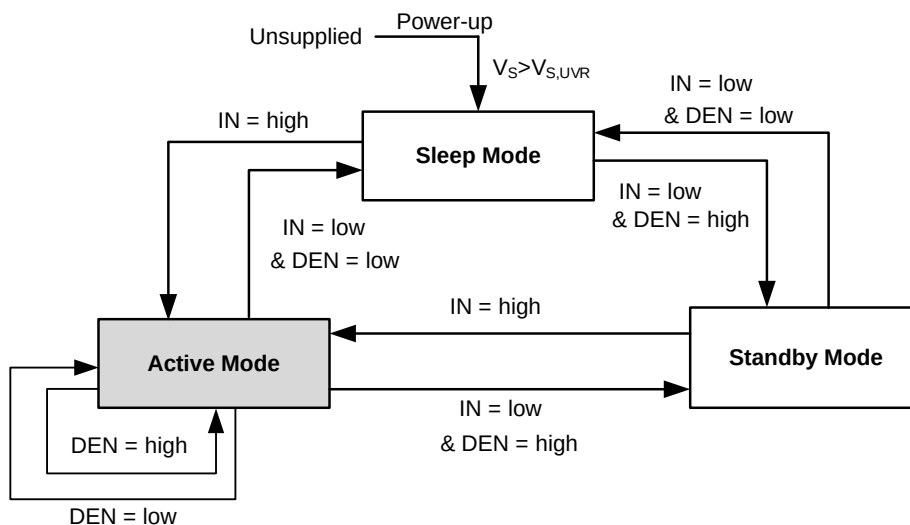


Figure 10-1. Operating Mode Diagram

10.1.1 Sleep Mode

During Sleep Mode, the output channel of the device is turned OFF. Current consumption is minimum (see parameter $I_{S,SLEEP}$). No overtemperature protection, overload protection or diagnostic functions are active in this mode.

10.1.2 Standby Mode

The device operates in Standby Mode when $DEN = \text{high}$ and $IN = \text{low}$. The output channel is OFF. Current consumption is specified as $I_{GND,STBY}$.

10.1.3 Active Mode

When the device is in Active Mode, the output channel is ON if no fault event occurs. Current consumption is specified as $I_{GND,ON}$ (measured at the GND pin). Overload and overtemperature protections are active. The diagnostic function is active when $DEN = \text{high}$.

10.2 Power Stages

10.2.1 Switching Resistive Loads

When switching resistive loads, the switching time and slew rates are shown in Figure 10-2.

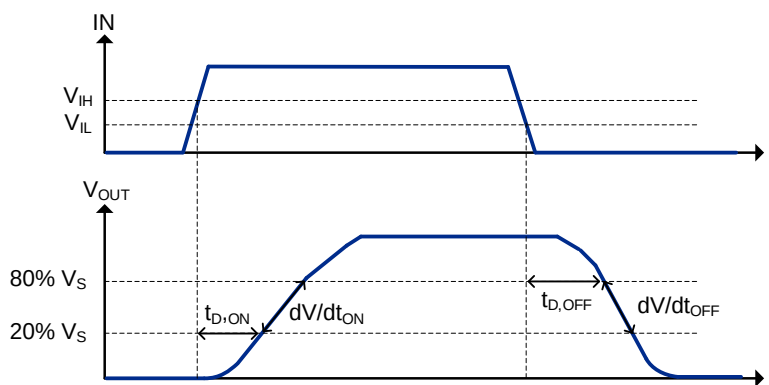


Figure 10-2. Switching a Resistive Load

10.2.2 Switching Inductive Loads

When turning OFF inductive loads with high-side switches, the output voltage V_{OUT} drops to a negative potential, because the inductance tends to maintain the current flow. To prevent the device from damage due to overvoltage, a voltage clamp mechanism is implemented. The clamping mechanism limits the negative output voltage to a safe value. Figure 10-3 shows a concept drawing of implementation.

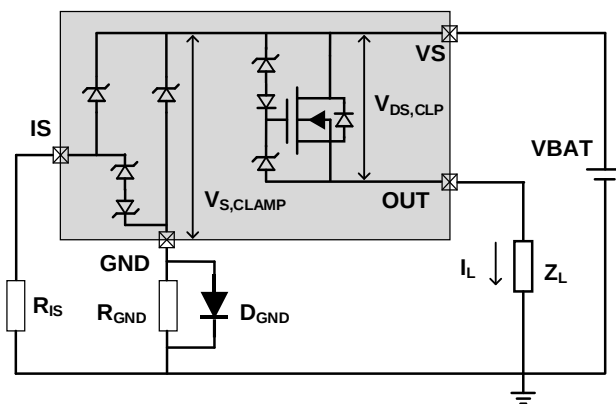


Figure 10-3. Output Clamp Diagram

10.3 Protections

10.3.1 Overtemperature Protection

To prevent the junction temperature from exceeding the threshold, the device features both absolute thermal shutdown (T_{SD}) and dynamic thermal swing shutdown (T_{SW}) protection mechanisms. Once the temperature exceeds the threshold T_{SD} , or the temperature swing exceeds the threshold T_{SW} , the overheated channel is turned OFF and remains OFF until T_J has reached the "Auto-restart" condition described in Chapter 10.3.5. Figures 10-4 and 10-5 respectively demonstrate these two overtemperature protection mechanisms. $T_{J,REF}$ is the reference temperature used for dynamic temperature protection.

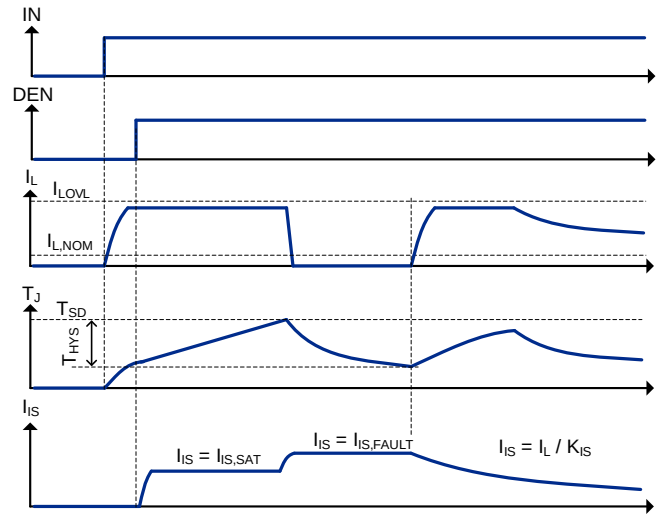


Figure 10-4. Overtemperature Protection (Thermal Shutdown)

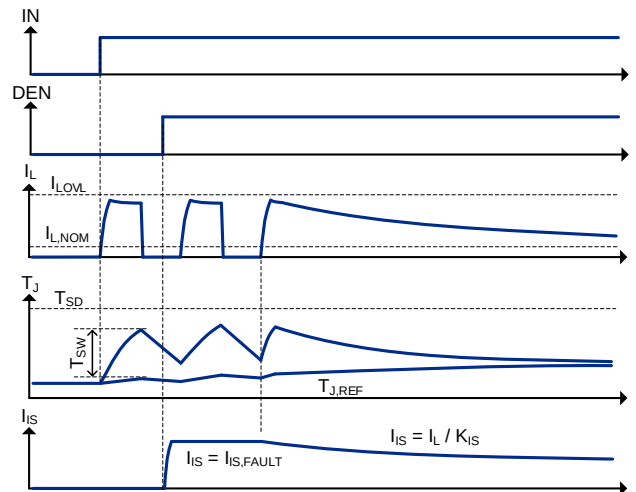


Figure 10-5. Overtemperature Protection (Thermal Swing Shutdown)

10.3.2 Overload Protection

The device features protection against overload and short circuit to ground. Its overload threshold decreases as junction temperature rises: at high temperatures, the overload threshold is reduced to prevent device damage. When the supply voltage V_S exceeds $V_{S,JS}$ (during load dump or jump start), the overload detection current decrease to $I_{LOVL,JS}$ as shown in Figure 10-6.

Once the load current meets or exceeds the applicable overload threshold, the output channel is switched off. The channel is allowed to restart according to the auto-restart strategy described in Chapter 10.3.5.

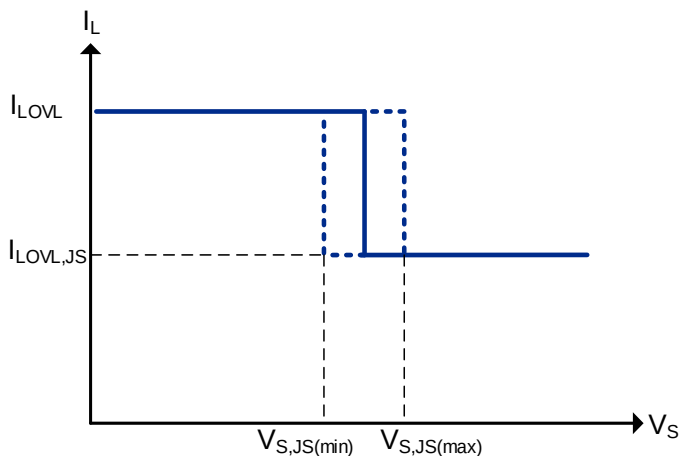


Figure 10-6. Overload Detection Current Variation with VS Voltage

10.3.3 Undervoltage Protection

Undervoltage protection monitors the supply voltage (V_S). If V_S drops below the minimum undervoltage threshold ($V_{S,UVF}$), the output is turned off regardless of the input status. As soon as V_S is above the operative threshold ($V_{S,UVR}$), the channel is switched ON again as shown in Figure 10-7.

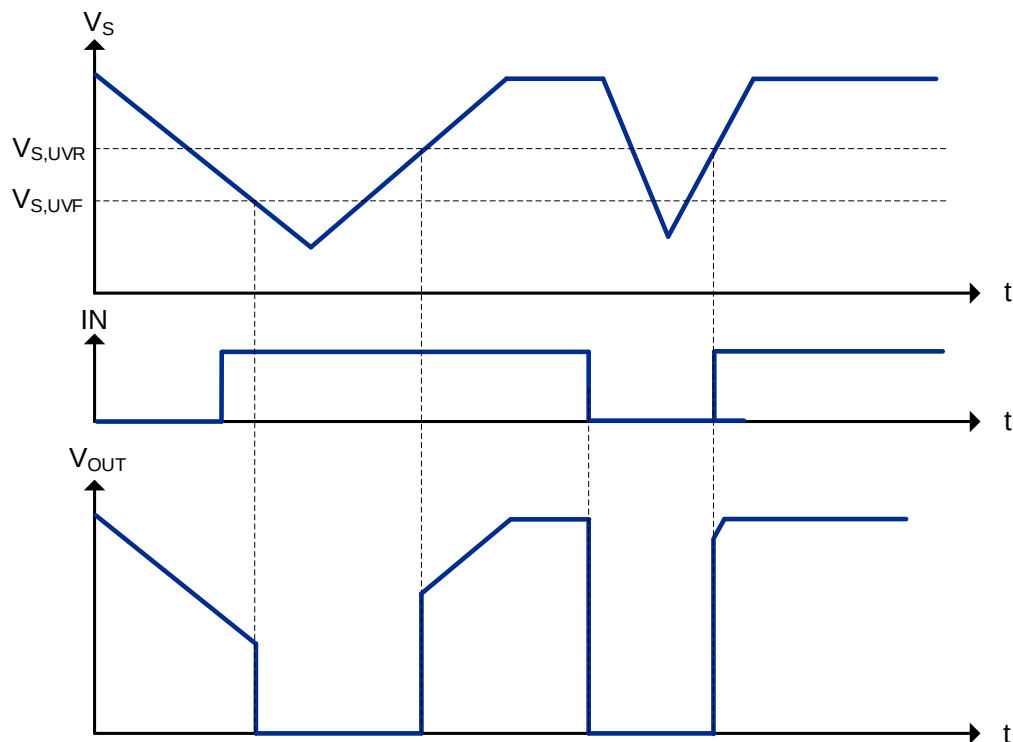


Figure 10-7. VS Undervoltage Protection

10.3.4 Loss of Ground Protection

In the event of Loss of Ground, the device automatically switches off the power MOSFET, ensuring no current flows into the load. It is recommended to connect a resistor between any logic pins and the microcontroller to ensure the channel switch OFF.

Note: In case any logic pin is pulled to ground (either by a resistor or active) a parasitic ground path is available, which could keep the device operational during loss of device ground.

10.3.5 Auto-restart Strategy

The auto-restart strategy is a protection mechanism designed to ensure device safety and reliability. When a protection event occurs during $IN = \text{high}$, the channel is switched off and the IS pin outputs a fault current $I_{IS, \text{FAULT}}$ in case of $DEN = \text{high}$.

The channel can be allowed to restart automatically if the “restart” conditions for the protection mechanisms are fulfilled:

- For overtemperature: $T_J < T_R$ and $T_J - T_{J, \text{REF}} < T_{\text{SW}} - T_{\text{HYS}}$ (including hysteresis).
- For overload: $I_L < 50\text{mA}$ and T_J within T_{SD} and T_{SW} ranges (including hysteresis).

The auto-restart strategy timing diagram as shown in Figure 10-8.

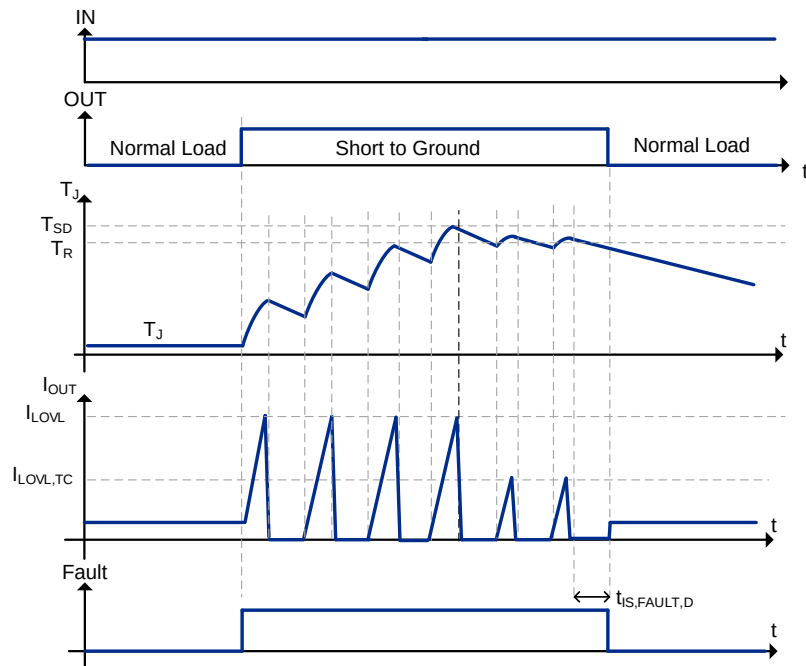


Figure 10-8. Auto-restart strategy

10.4 Diagnosis

The device integrates comprehensive diagnostic capabilities via IS pin, which delivers proportional current sense signals or fault indications when $DEN = \text{high}$. When $DEN = \text{low}$, the IS pin enters a high-impedance state. A sense resistor (R_{IS} , typically $1.2\text{k}\Omega$) must be connected between the IS pin and module ground to limit power dissipation. Table 10-1 gives a quick reference to the multiplexed output state of the IS pin during the device operation.

Table 10-1. Sense Signal, Function of Application Condition

Conditions	IN	DEN	OUT	IS
Normal Operation	Low	High	~GND	Z
Short Circuit to GND			~GND	Z
Overtemperature			Z	I _{IS,FAULT}
Short Circuit to V _S			V _S	I _{IS,OLOFF}
Open Load			> V _{OL,OFF}	I _{IS,OLOFF}
Inverse Current			V _{OUT} > V _S	I _{IS,OLOFF}
Normal Operation	High		~V _S	I _{IS} = I _L / K _{IS}
Short Circuit to GND			~GND	I _{IS,FAULT}
Overload			< V _S	I _{IS,FAULT}
Overtemperature			Z	I _{IS,FAULT}
Short Circuit to V _S			V _S	I _{IS} < I _L / K _{IS}
Open Load			~V _S	I _{IS} = I _{IS,LEAK2}
Inverse Current			V _{OUT} > V _S	I _{IS} = I _{IS,LEAK2}
All Conditions	n.a.	Low	n.a.	Z

10.4.1 Diagnosis in Active Mode

Diagnosis in Active Mode is enabled when DEN = high and diagnostic signals are delivered via the IS pin. It includes two functions: proportional current sense and fault indications.

When no faults are present, the IS pin outputs an analog current I_{IS} proportional to the load current I_L , following the ratio $K_{IS} = I_L / I_{IS}$. An external RC filter is recommended for the IS pin to reduce signal ripple.

If overtemperature, overload, or short circuit to ground occurs, the IS pin outputs a fault current $I_{IS,FAULT}$ as long as diagnosis is enabled.

10.4.2 Diagnosis in Standby Mode

Diagnosis is activated in Standby Mode. The open load detection signal is delivered via the IS pin.

The device compares the voltage V_{OUT} with the threshold voltage $V_{OL,OFF}$ to detect load conditions. If open load occurs ($V_{OUT} \geq V_{OL,OFF}$), the IS pin outputs an open load fault current ($I_{IS,OLOFF}$). To differentiate open load and short circuit to V_S , an external switch and a pull-up resistor are recommended. It is necessary to wait a time $t_{D,OL,IN}$ between the falling edge of the input pin and the sensing at pin IS for Open Load in Standby Mode to allow the internal comparator to settle (see Figure 10-9).

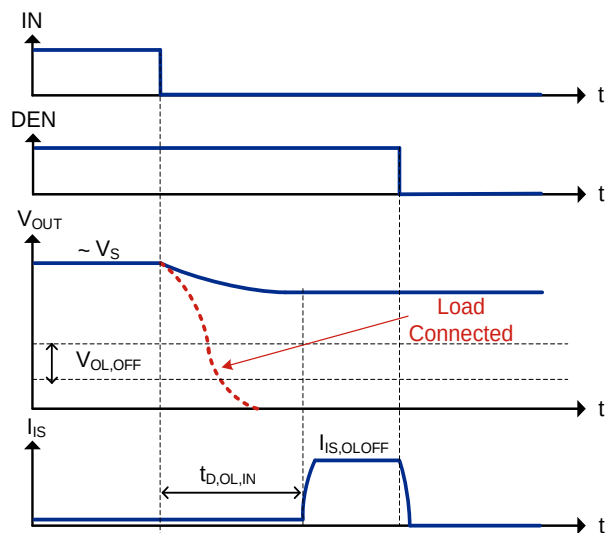


Figure 10-9. Timings for an Open Load Detection

10.4.3 Sense Time

Sense timings of the device define the response characteristics of the IS pin during IN/DEN activation and deactivation, with all parameters are specified under the test conditions given in Section 8.5. Figure 10-10 presents the sense settling and disabling time.

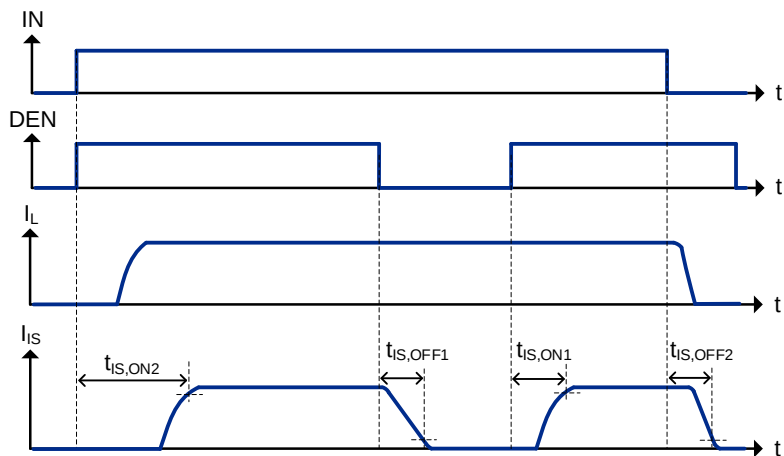
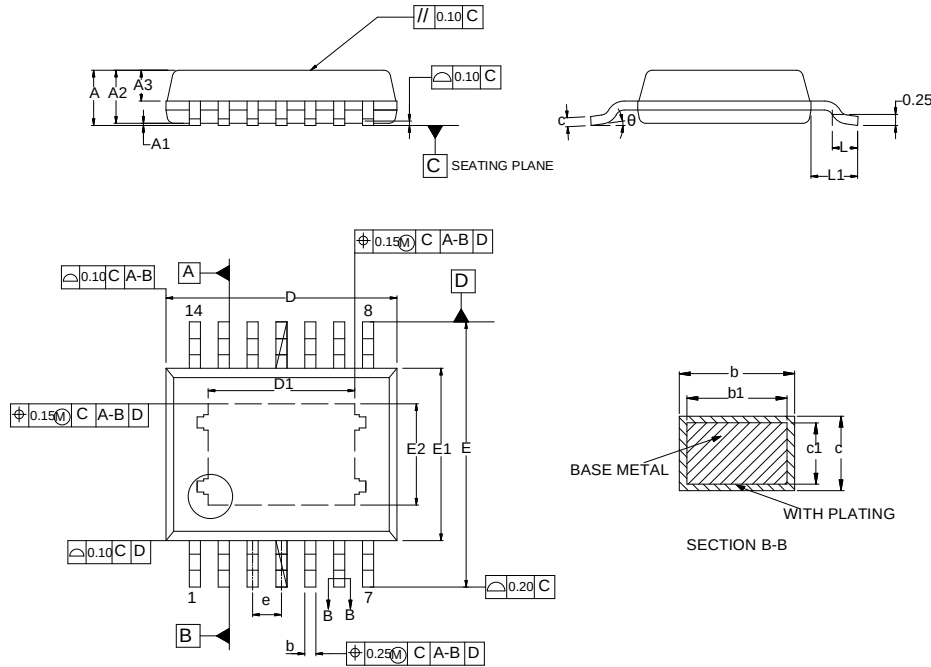


Figure 10-10. Sense Settling and Disabling Time

MECHANICAL DATA

eSSOP-14

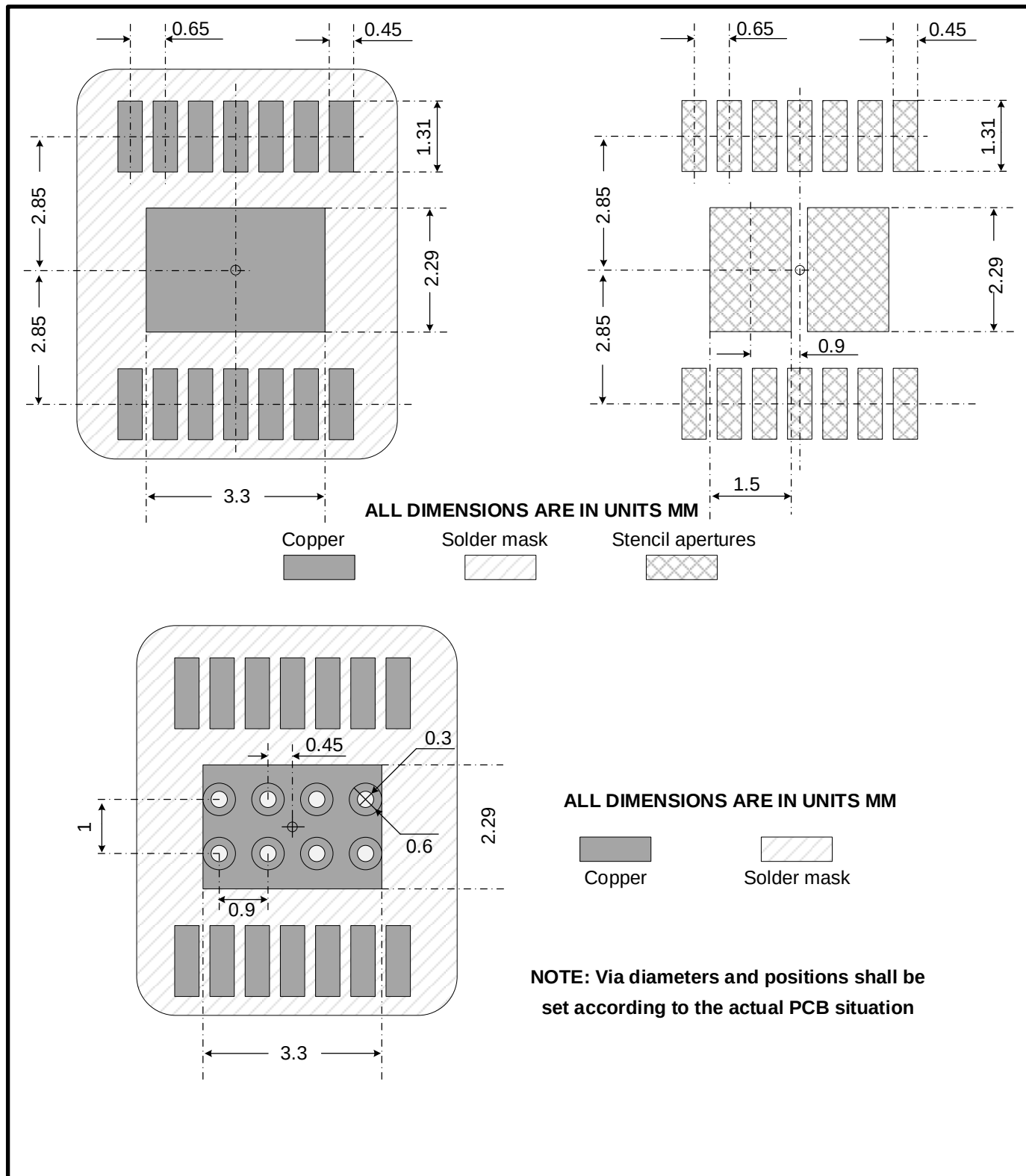


SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	—	—	1.40
A1	0.00	—	0.10
A2	1.10	1.20	1.30
A3	0.60	0.70	0.80
b	0.23	—	0.31
b1	0.22	0.25	0.28
c	0.20	—	0.24
c1	0.19	0.20	0.21
D	5.10	5.20	5.30
E	5.80	6.00	6.20
E1	3.80	3.90	4.00
e	0.65BSC		
L	0.40	0.57	0.80
L1	1.05REF		
θ	0	—	8°

Size(mm)	E2	D1
98*138	2.29±0.30	3.30±0.30

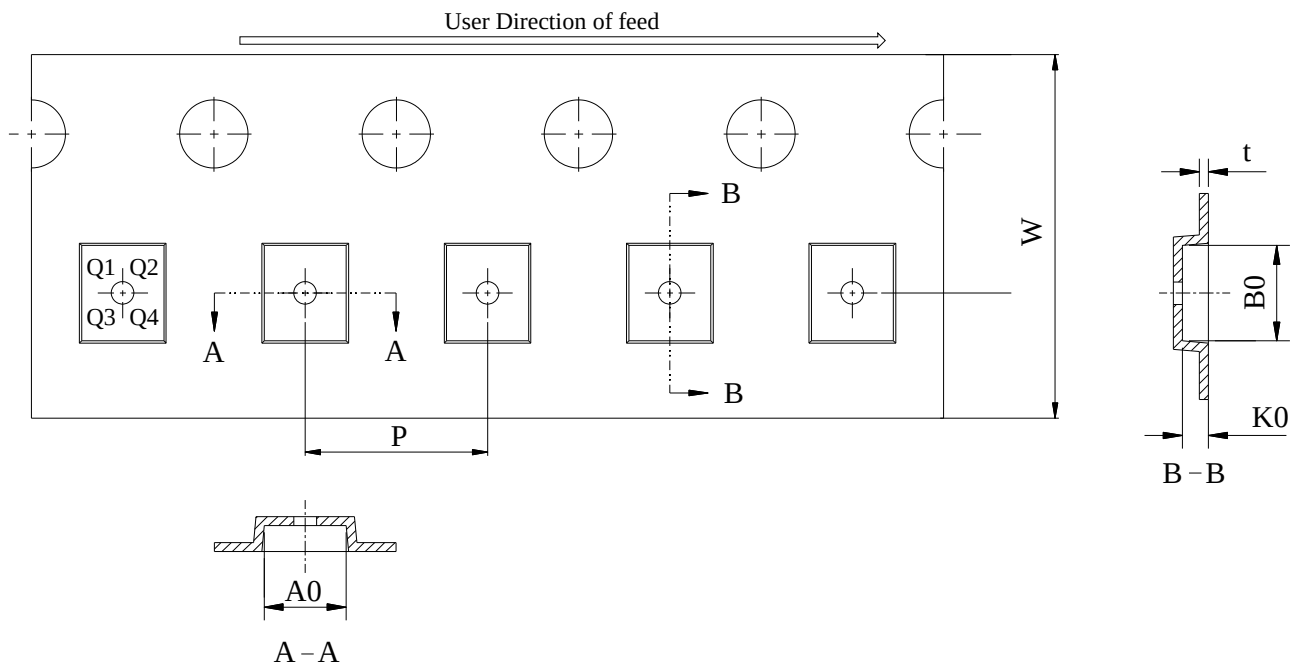
RECOMMENDED FOOTPRINT

eSSOP-14



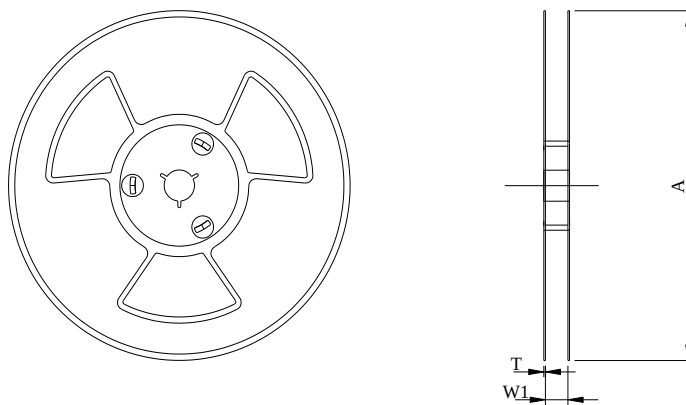
TAPE AND REEL INFORMATION

Carrier Tape



Item	W	P	A0	B0	K0	t	Pin1 Quadrant
Size (mm)	12.00+0.30/-0.1	8.00±0.10	6.50±0.10	5.50±0.10	1.75±0.10	0.30±0.05	Q1

REEL



Item	A	W1	T
Size (mm)	330±1	12.4 +1/-0	2.1±0.3

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